

Development of a High Counting Rate ASIC for Heavy-ion Beam Monitoring

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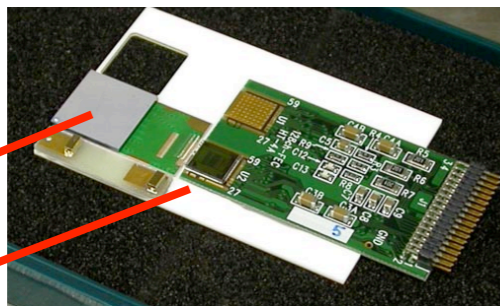
Tadayuki Takahashi, ISAS/JAXA

ASIC Dev. Activities at ISAS/JAXA

for X-ray & Gamma-ray astronomy

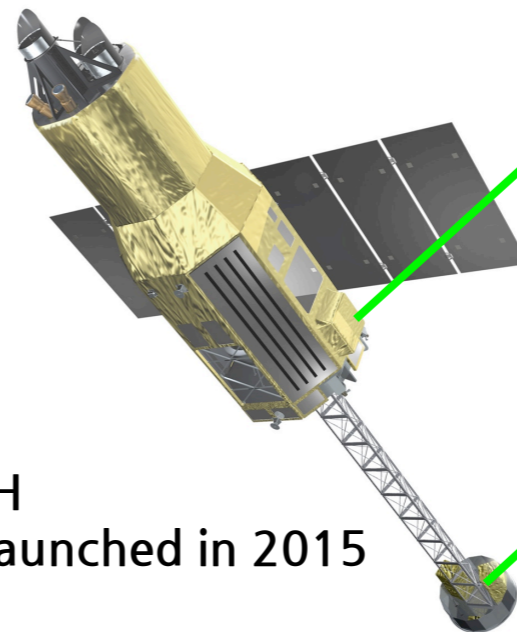
► Collaboration with GM-IDEAS

VATA series ASICs specifically optimized for CdTe/Si pixel/strip detectors



CdTe

ASIC (ISAS/SLAC/IDEAS)



Astro-H
to be launched in 2015



Soft
Gamma-ray
Detector

Watanabe's talk



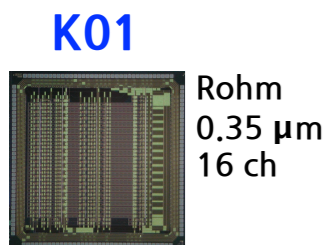
Hard
X-ray
Imager

► Original developments

Lead by Profs. Ikeda, & Takahashi

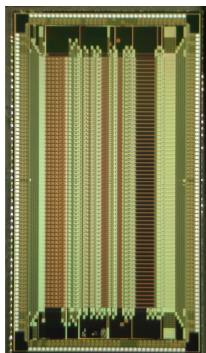
Several years of basic developments, ...
Now in the real application phase!

1-D ASICs



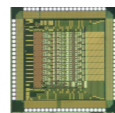
K01

Rohm
0.35 μm
16 ch



K02

TSMC
0.35 μm
64 ch
120 μm pitch



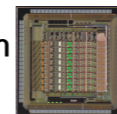
KW01

TSMC
0.35 μm
8 ch



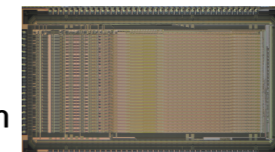
KW03

TSMC
0.35 μm
32 ch



KW04

TSMC
0.35 μm
32 ch



KW04C32

XFAB 0.35 μm
32 ch

KW04D64
Application to
Compton Camera
Harayama's
Poster

2003

2005

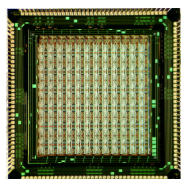
2007

2009

2011

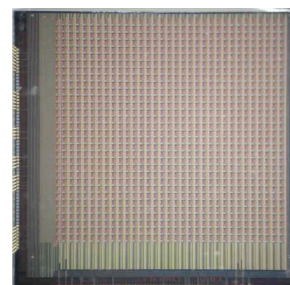
2013

2-D ASICs



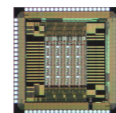
H01

Rohm
0.35 μm
12 x 12 ch
260 μm pitch



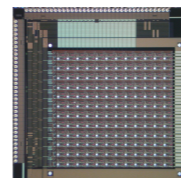
H02

TSMC
0.25 μm
32 x 32 ch
200 μm pitch



H03

TSMC
0.35 μm
4 x 4 ch
270 μm pitch



H04

TSMC
0.35 μm
12 x 12 ch
270 μm pitch

BPM01A40
Application to
Beam monitor
This talk

Spin-off Dev. for Medical application

Collaboration with Dr. Torikai (Gunma Univ.) & Dr. Yamaguchi (JAEA)

"Heavy ion radiotherapy"



At Gunma heavy ion medical center:

C^{6+} pinpoint beam
 $\Phi \sim 3 \text{ mm } (6\sigma)$
 $10^{5-9} \text{ particle/s}$
 $140-400 \text{ MeV/nucleus}$

accelerated by Synchrotron up to 70% of light of speed
irradiated into deep tumors within the patient

Current beam monitors:

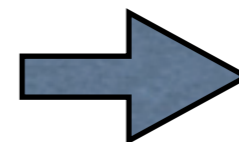
- Fluorescent screen (not transparent)
 - Need to be removed after position adjustment
 - => Takes hours for changing positions, painful for patients
- Strip line monitor
 - Works only in the current mode
 - Coarse resolution

Our plan:

Develop a **realtime beam monitor with fine pitch**

Si strip detectors (mostly transparent for C^{6+} beam)

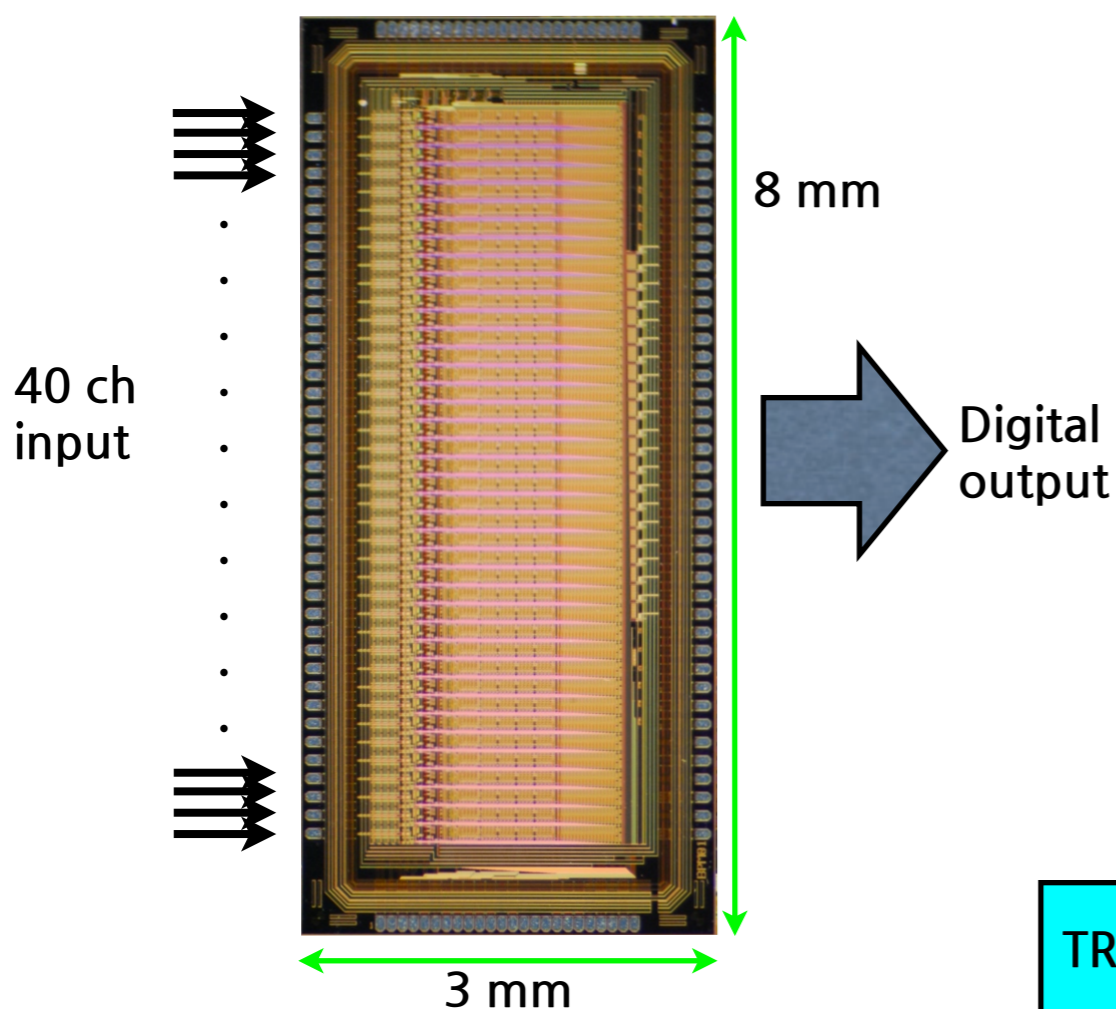
=> Precise measurement of the beam **position & shape**



To realize this, we need a high counting rate ASIC

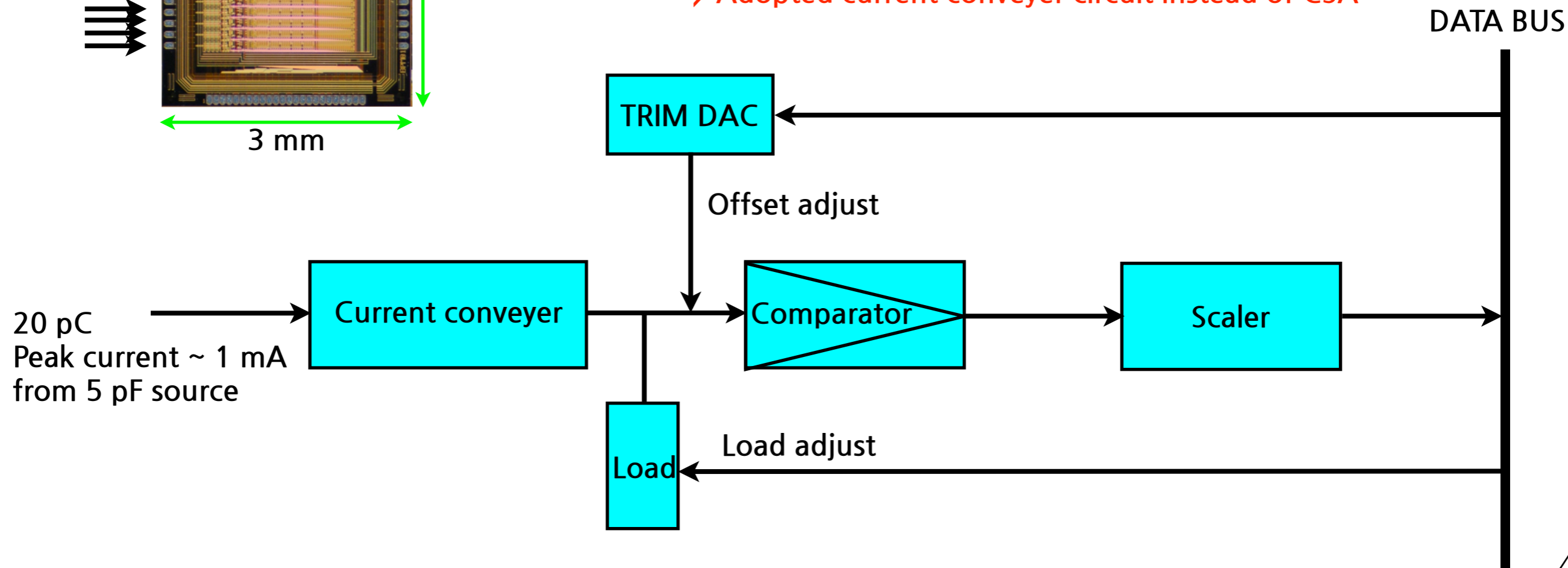
Development of a high counting rate ASIC

BMP01A40

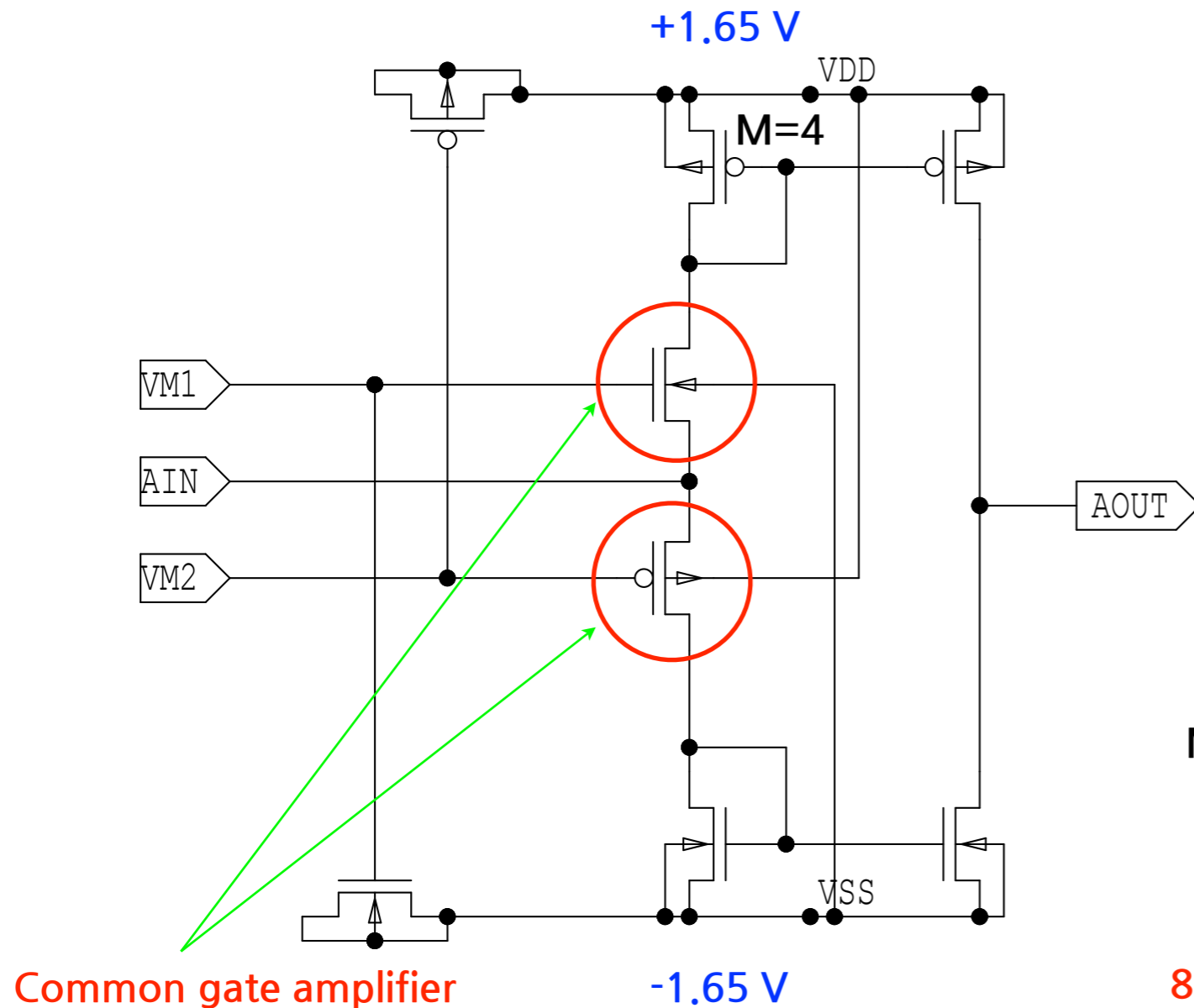


| | |
|--------------------|------------------------------|
| Process | XFAB 0.35 μm CMOS |
| Chip size | 8 mm x 3 mm |
| Pad pitch | 150 μm |
| Number of channels | 40 ch |
| Counter bits | 21 bits |
| Power supply | ± 1.65 V |
| Power consumption | 230 mW/chip |

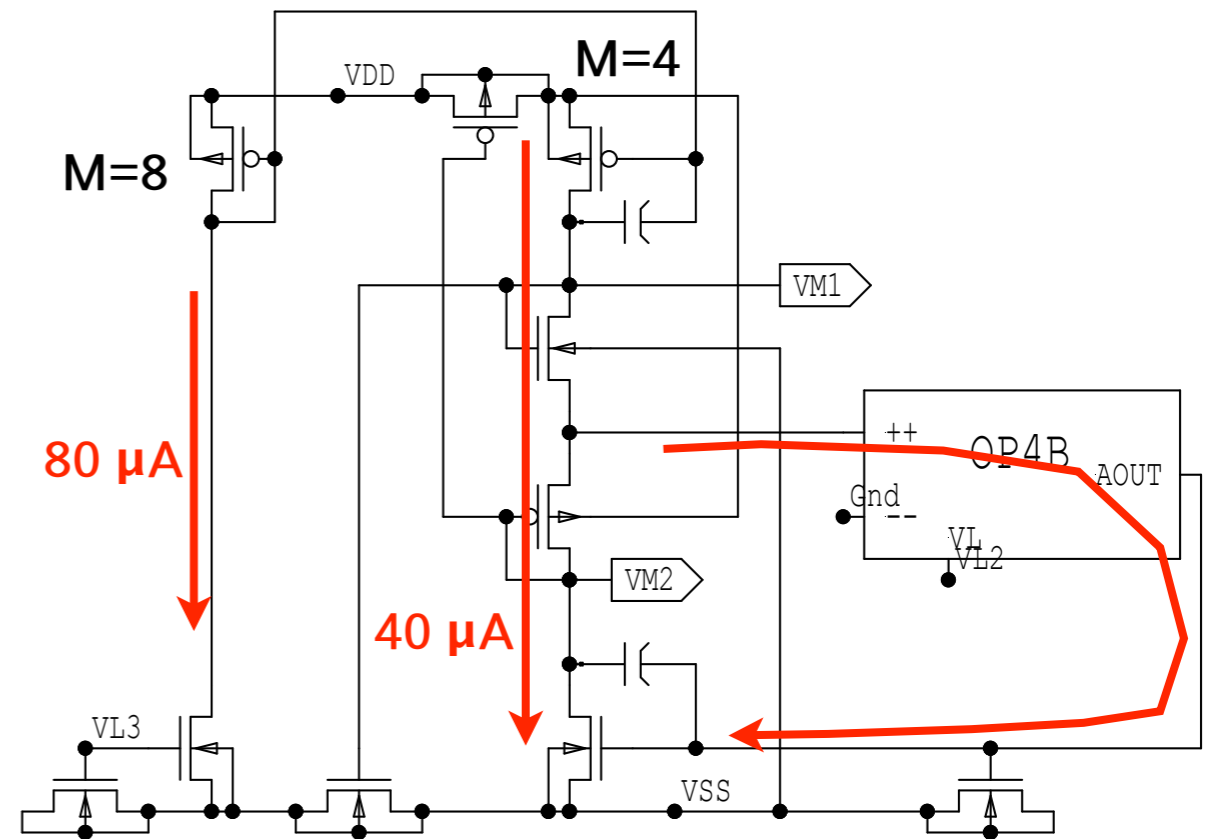
- ▶ Large input signal due to the heavy ions
 - ▶ Requirement for fast signal processing
- => Adopted current conveyer circuit instead of CSA**



Current conveyer circuit



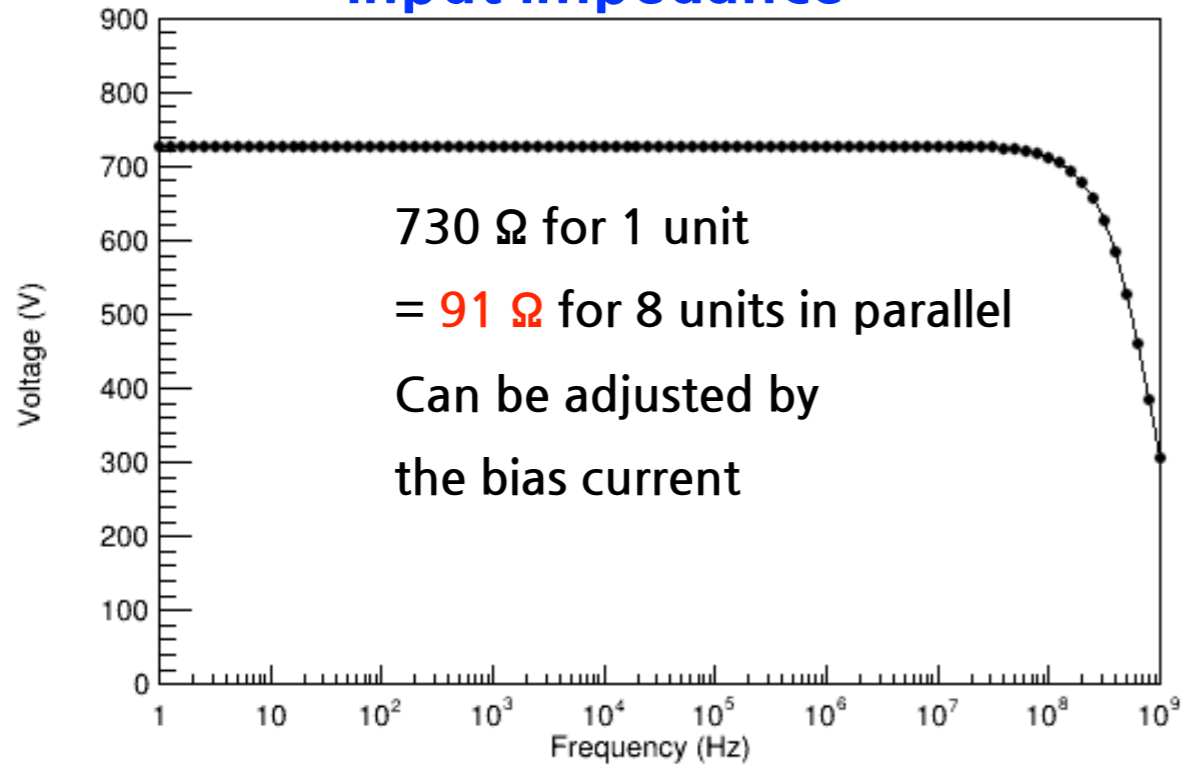
Bias circuit for VM1 & VM2



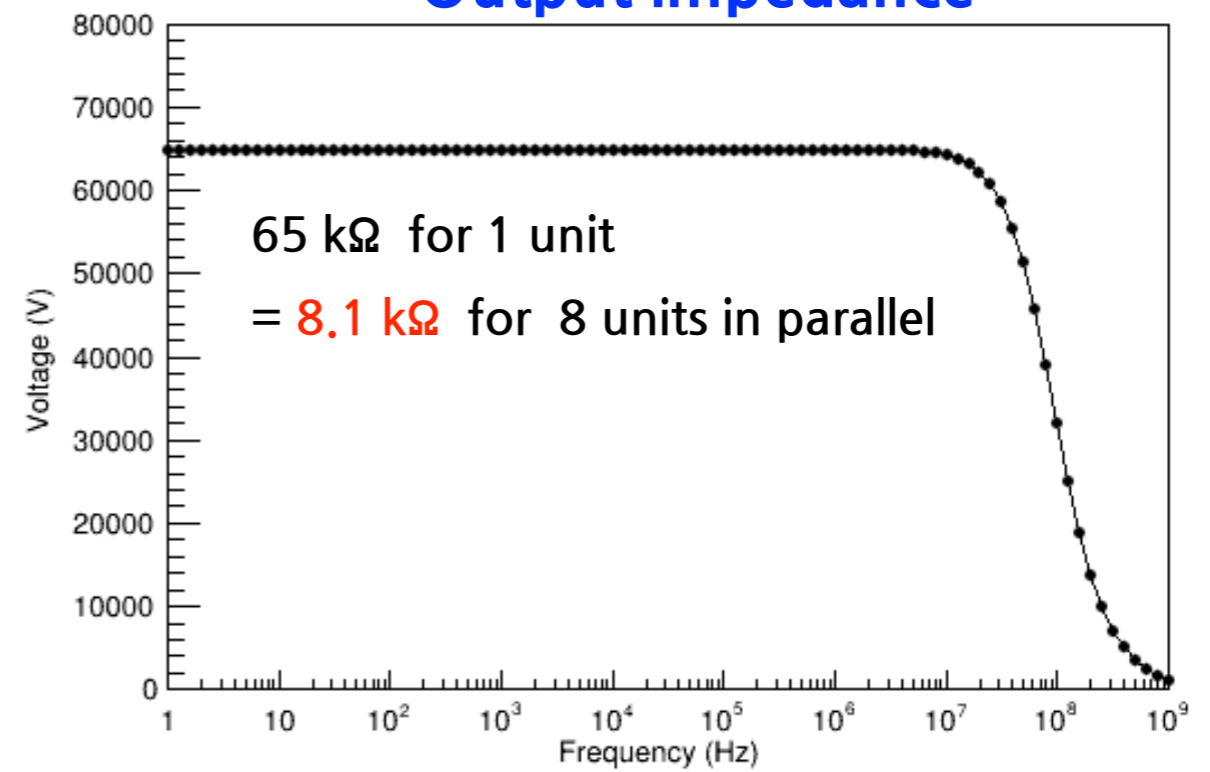
Negative feedback
Pins the the middle point to 0V

SPICE simulation

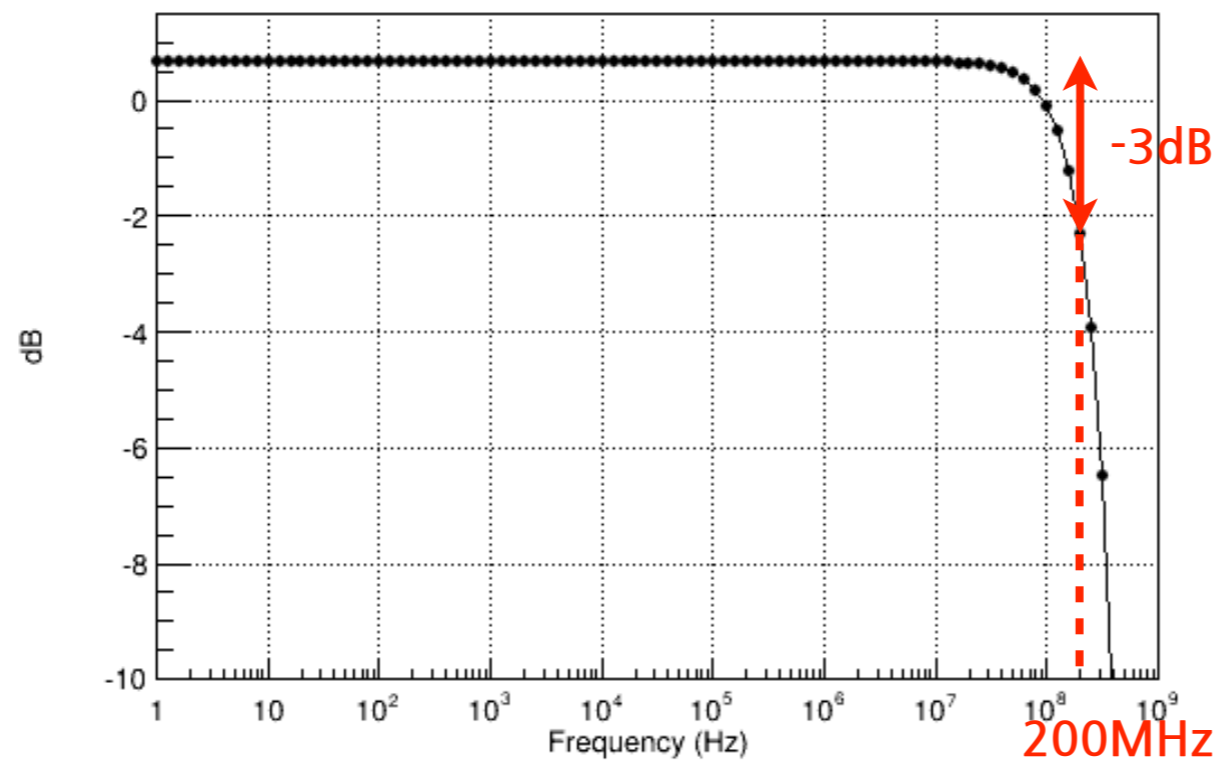
Input impedance



Output impedance

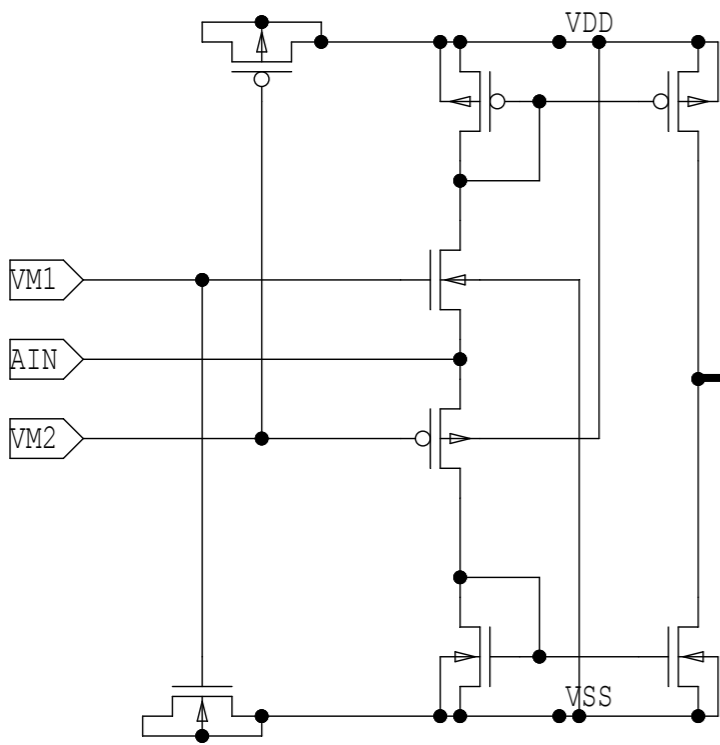


Transfer gain

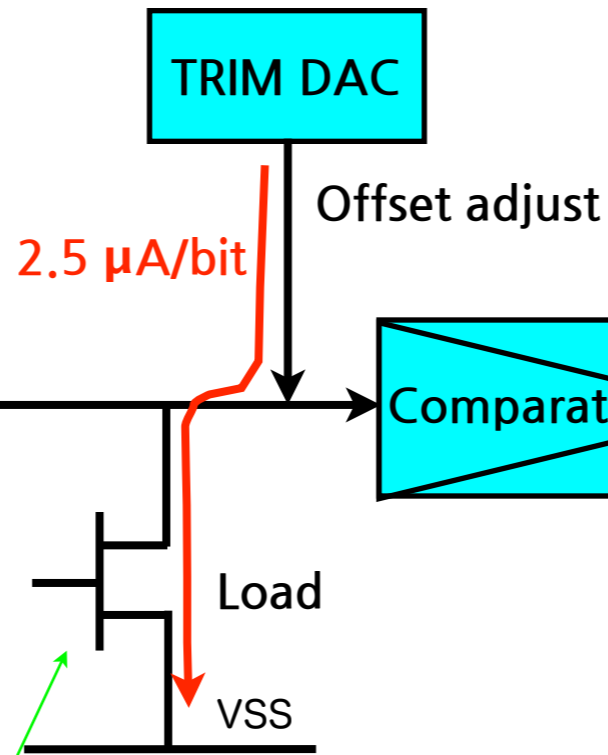


Block diagram & Waveforms

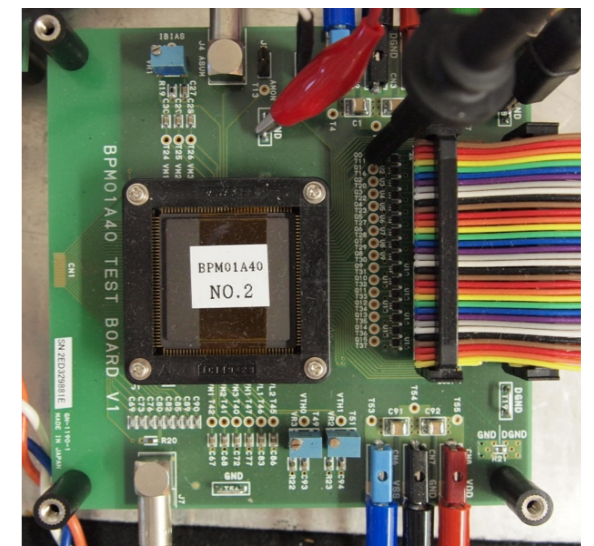
Current conveyer



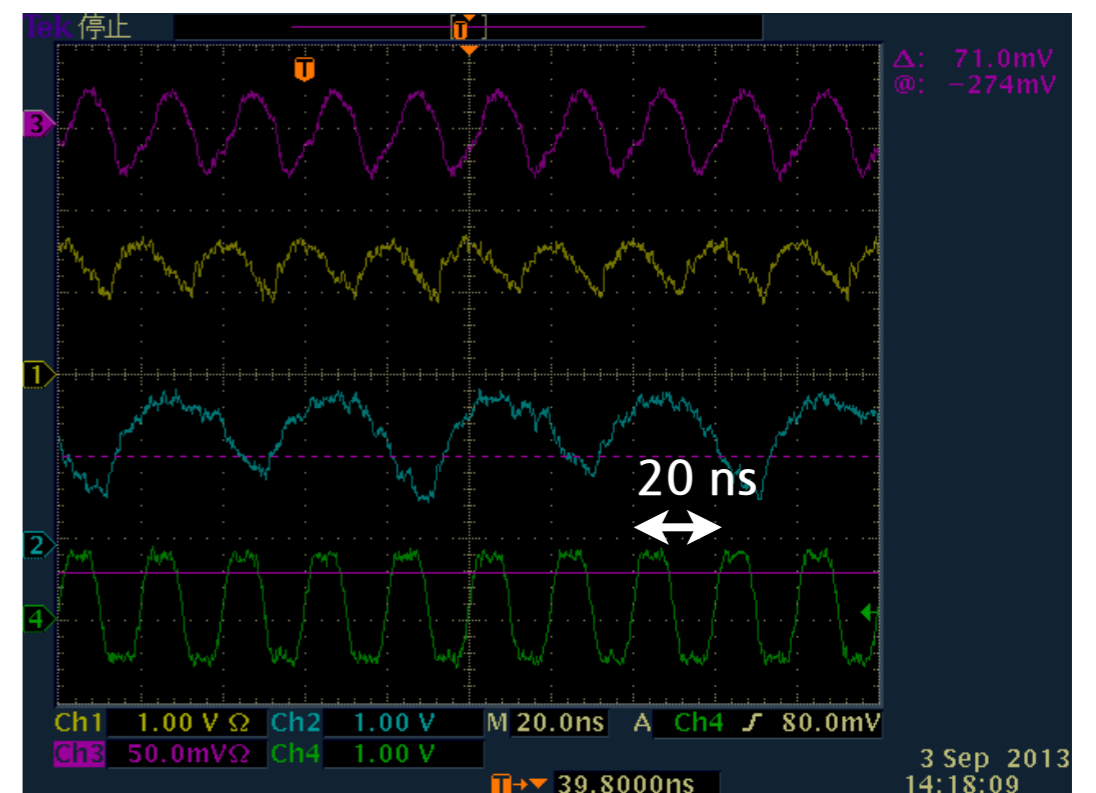
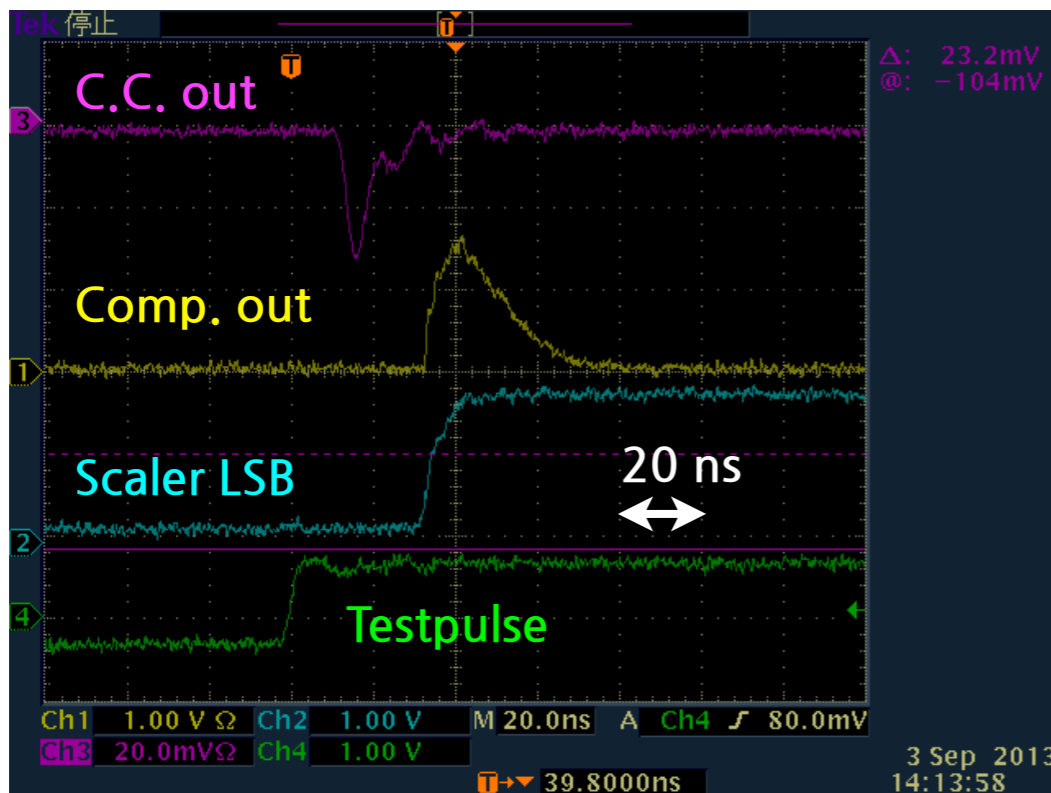
6-bit current DAC



Utilize NMOS on-resistance

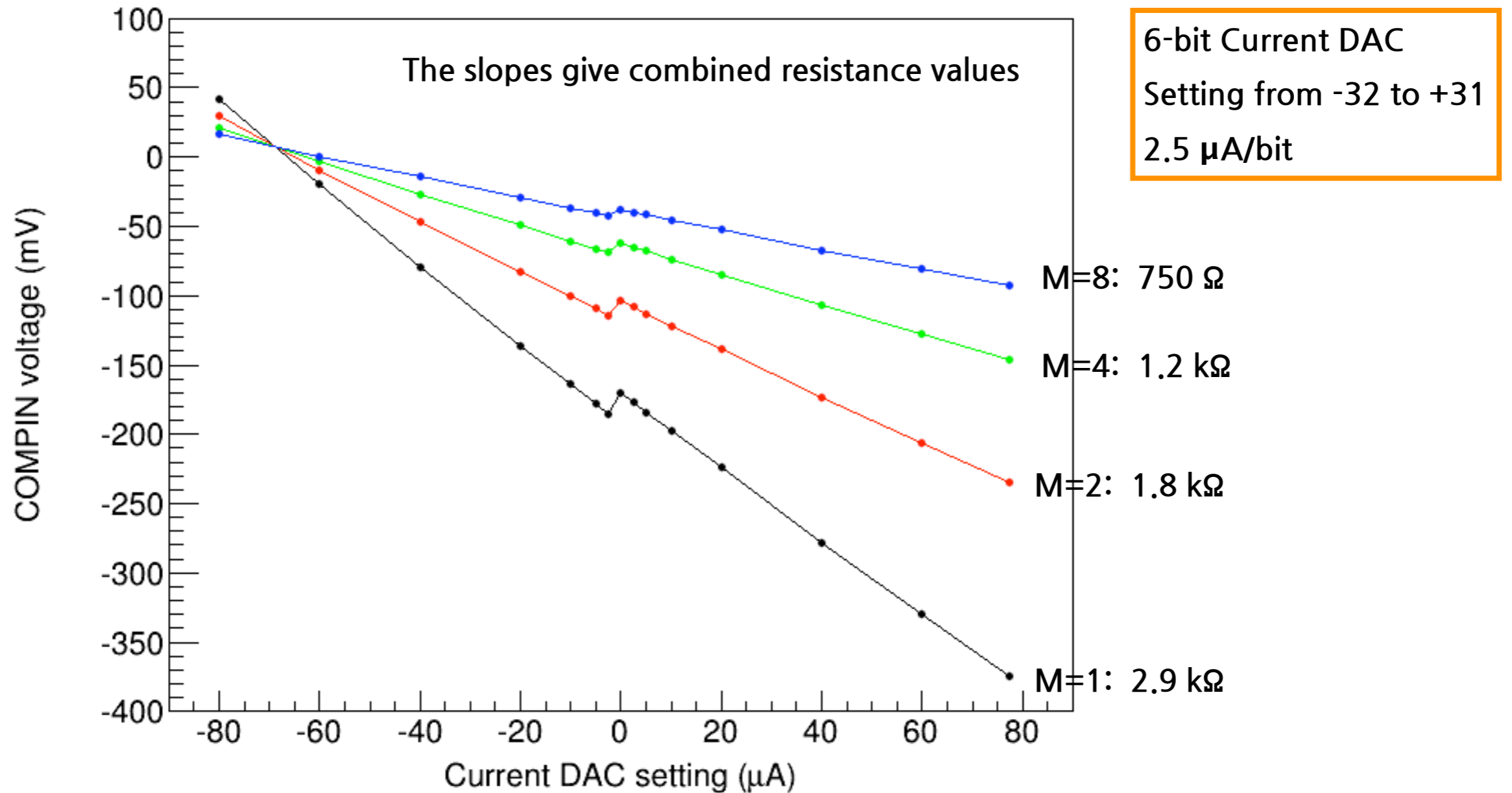


50 MHz square periodical test pulses are successfully counted with 0% loss (Maximum rate of the Pulse Generator)



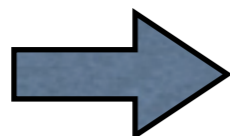
Impedance measurement using TRIM DAC

Relation between the baseline voltage & current DAC settings



※ Different lines correspond to different load values (# of parallel MOS resistors)

Combined resistance = $\frac{Z_o \cdot (R + Z_i)}{Z_o + (R + Z_i)}$



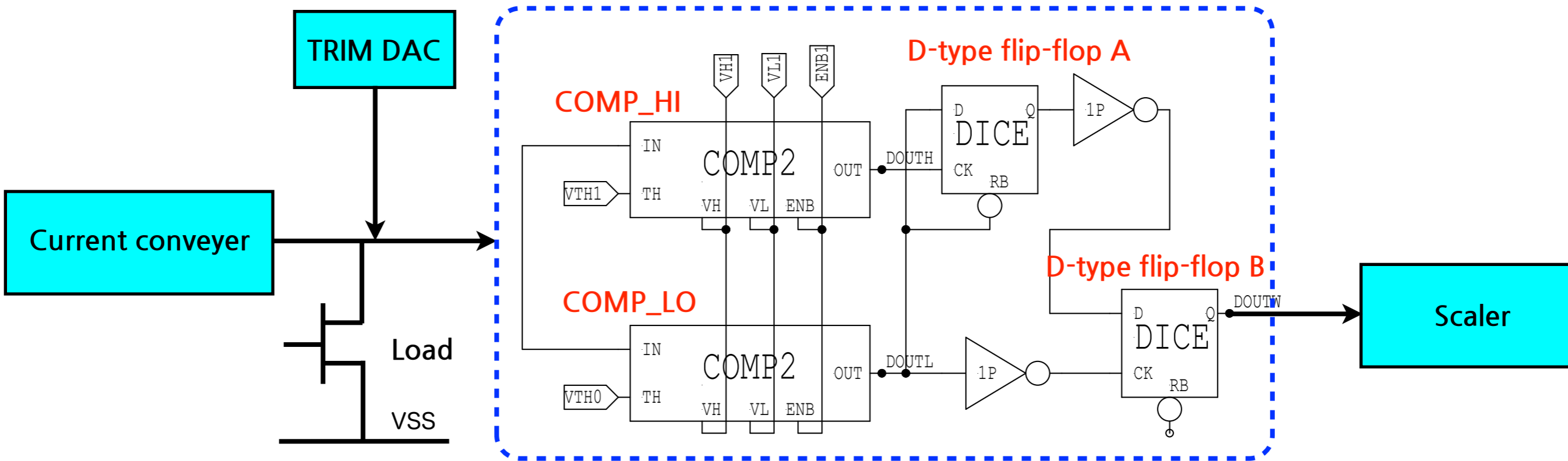
Input impedance of the C.C. = 89 Ω
Output impedance of the C.C. = 10.6 kΩ

consistent

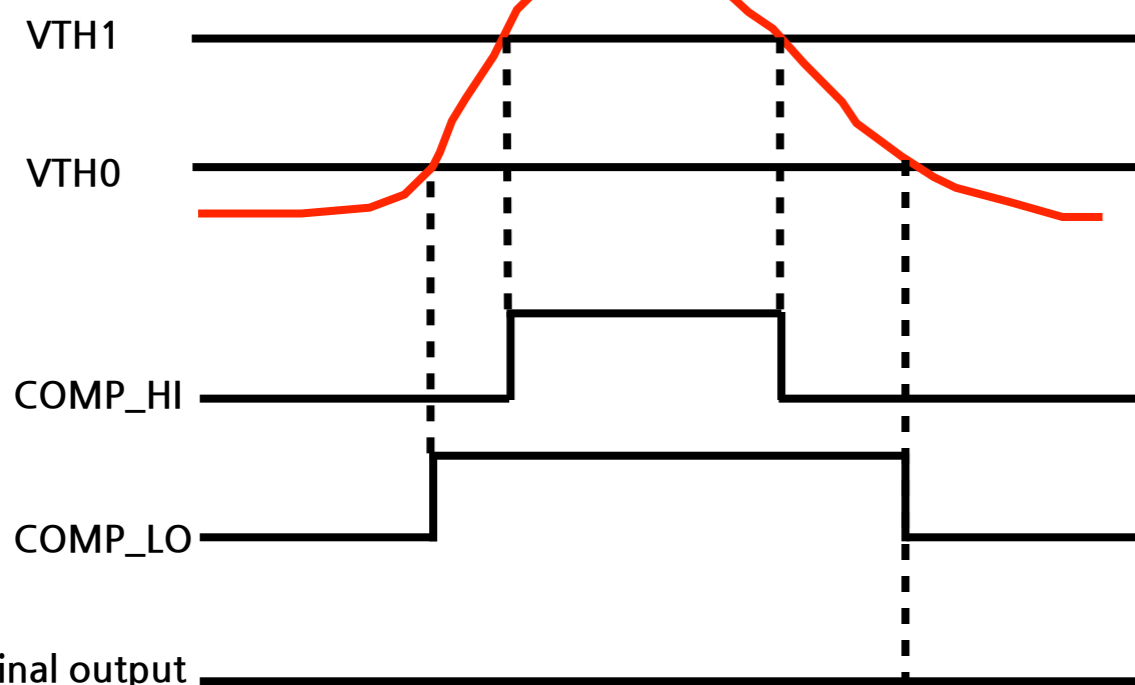
SPICE results
91 Ω
8.1 kΩ

Window comparator

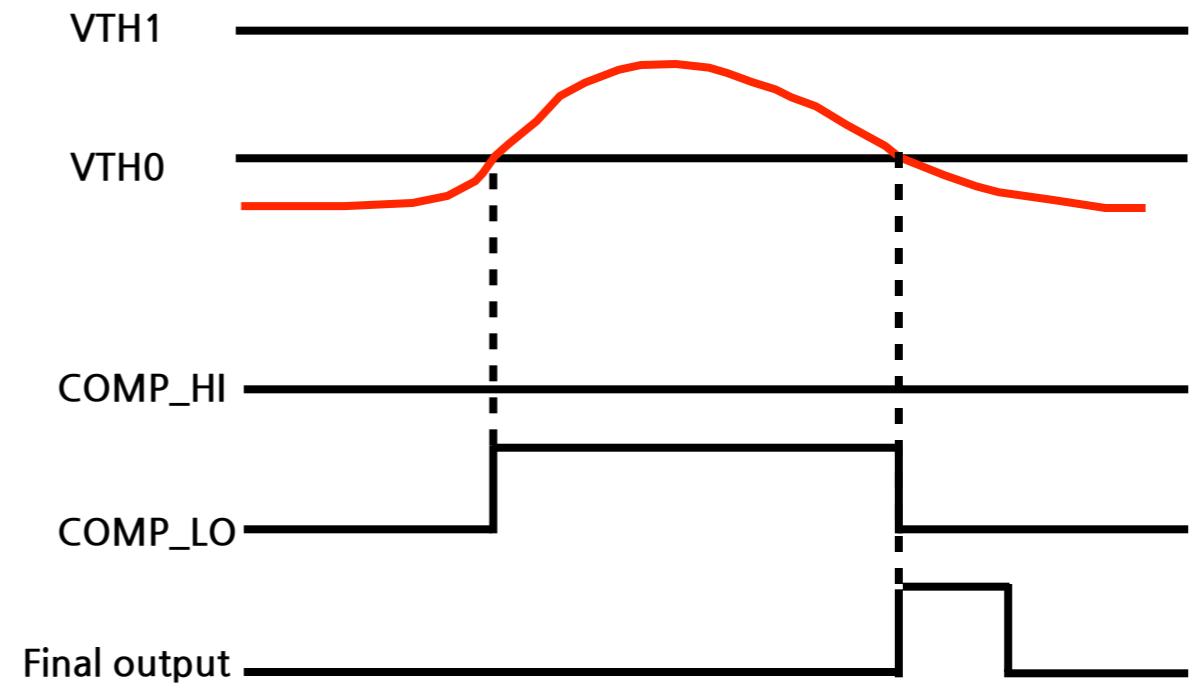
1. When COMP_LO is hit, F-F A is enabled
2. F-F A remembers whether COMP_HI is hit
3. At the falling edge of COMP_LO
F-F B makes the final judgement



Case 1: Does not count it



Case 2: Yes, count it!

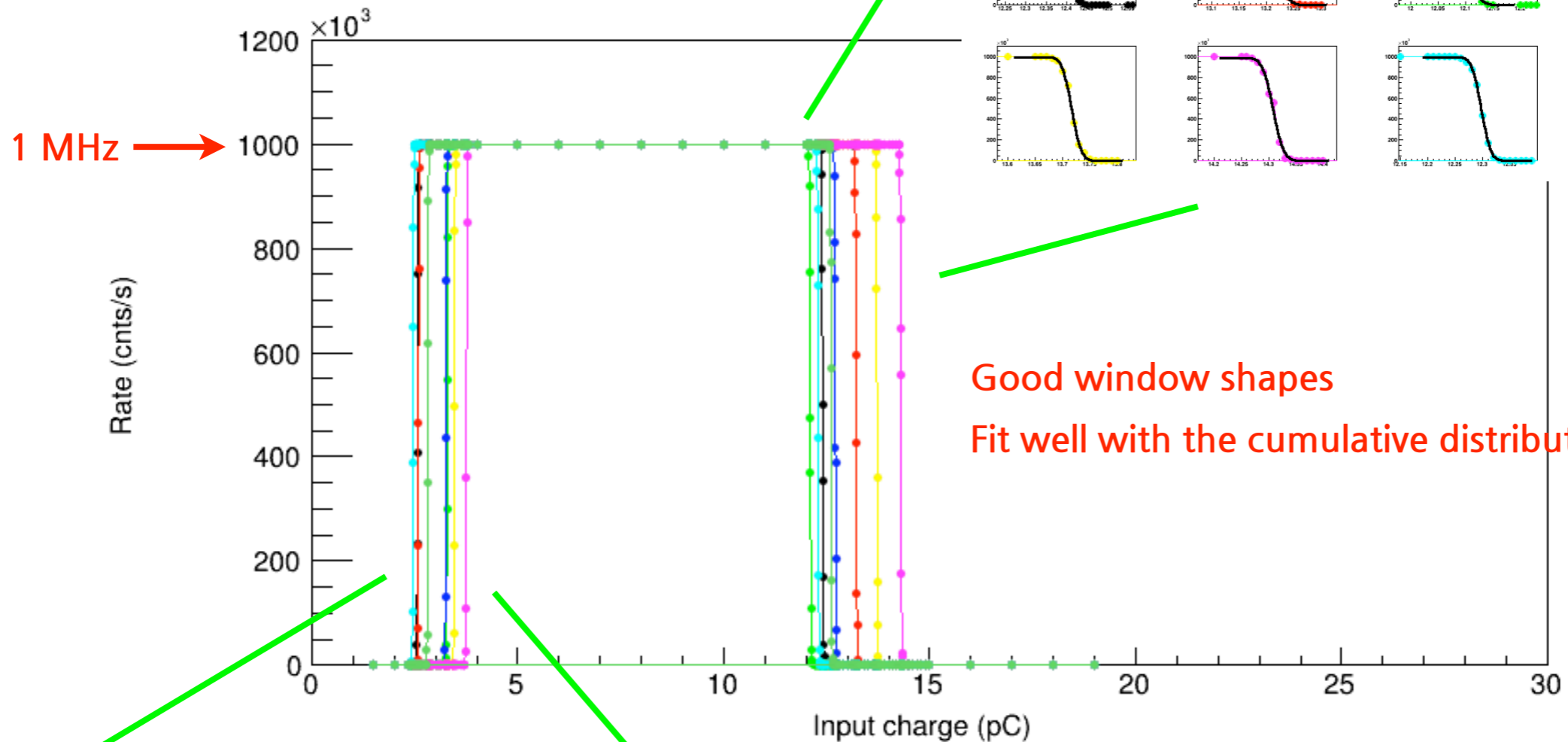
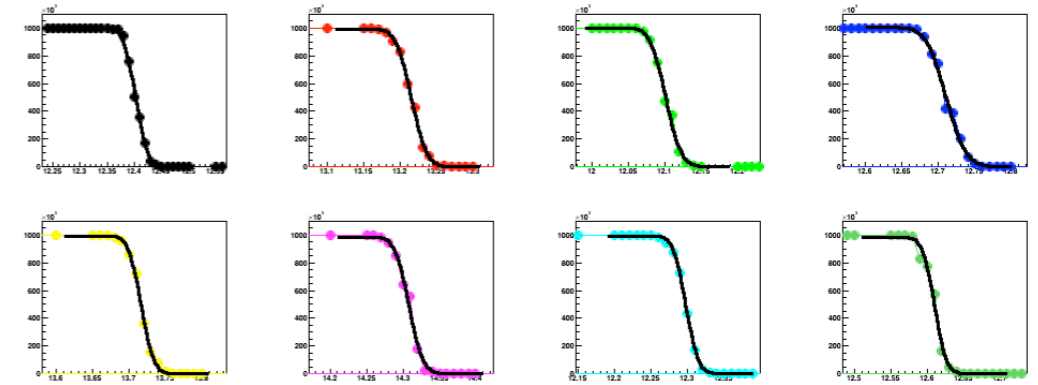


Window comparator performance

8 channels out of 40 were tested

1 MHz test pulse

Higher threshold dispersion: $\pm 9\%$



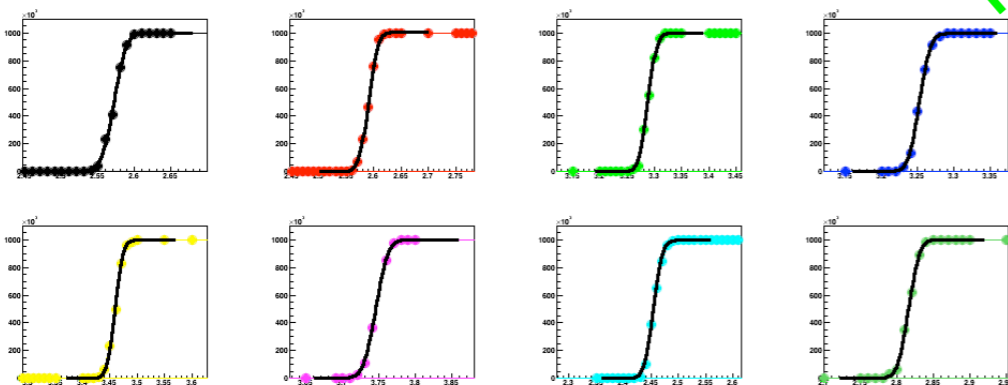
Good window shapes

Fit well with the cumulative distribution function

VTH0: -100 mV

VTH1: -300 mV

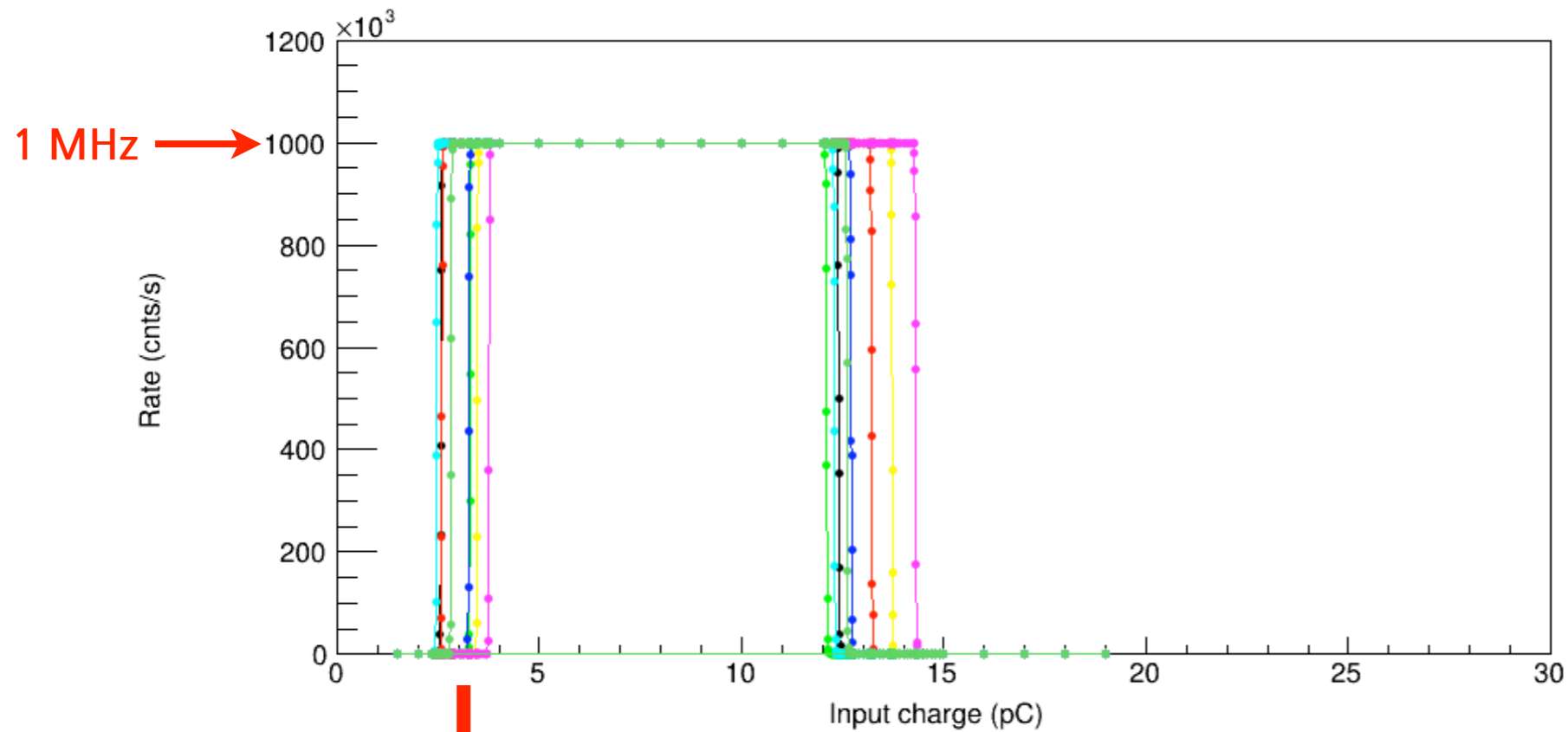
Lower threshold dispersion: $\pm 20\%$



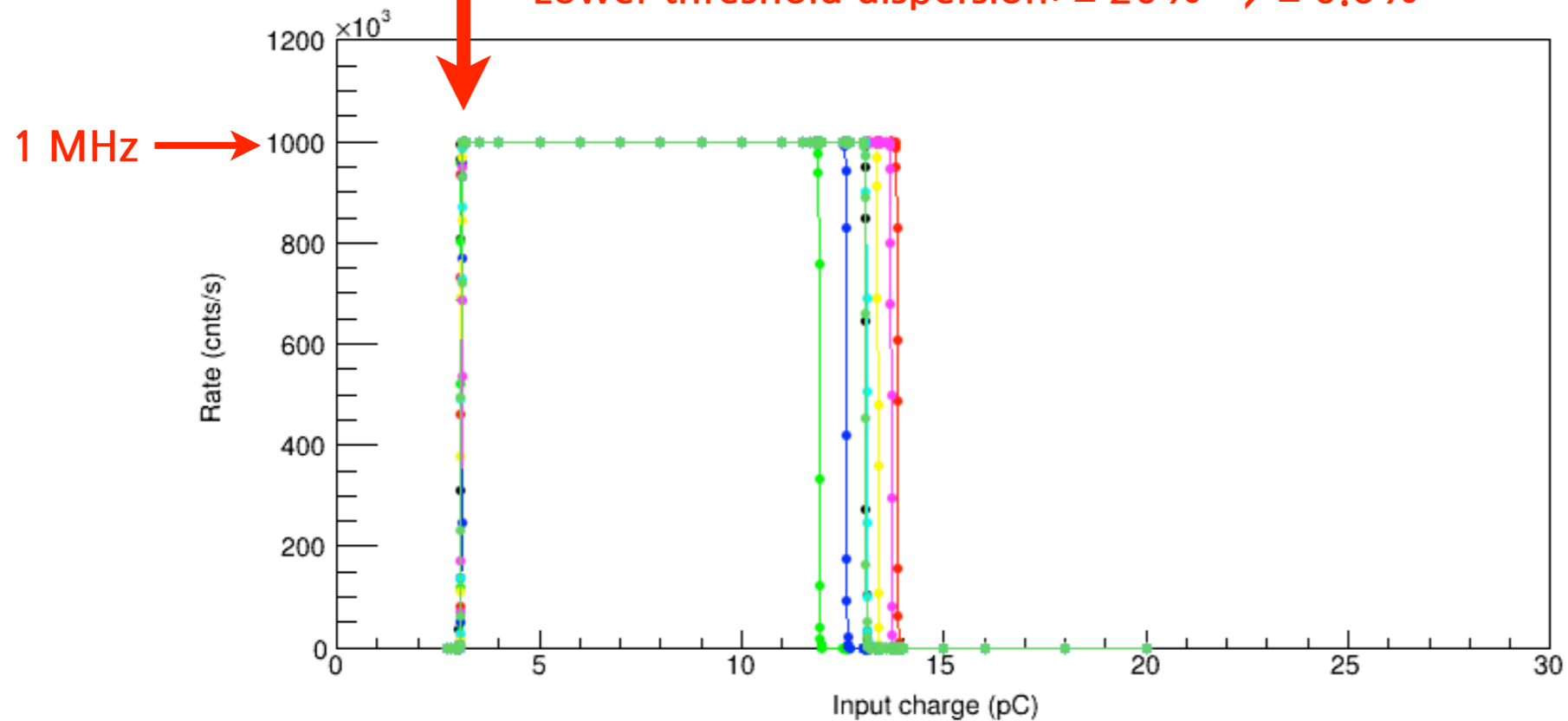
Gain dispersion: $\pm 9\%$

Noise distribution: 12~22 fC

Offset adjustment by TRIM DAC



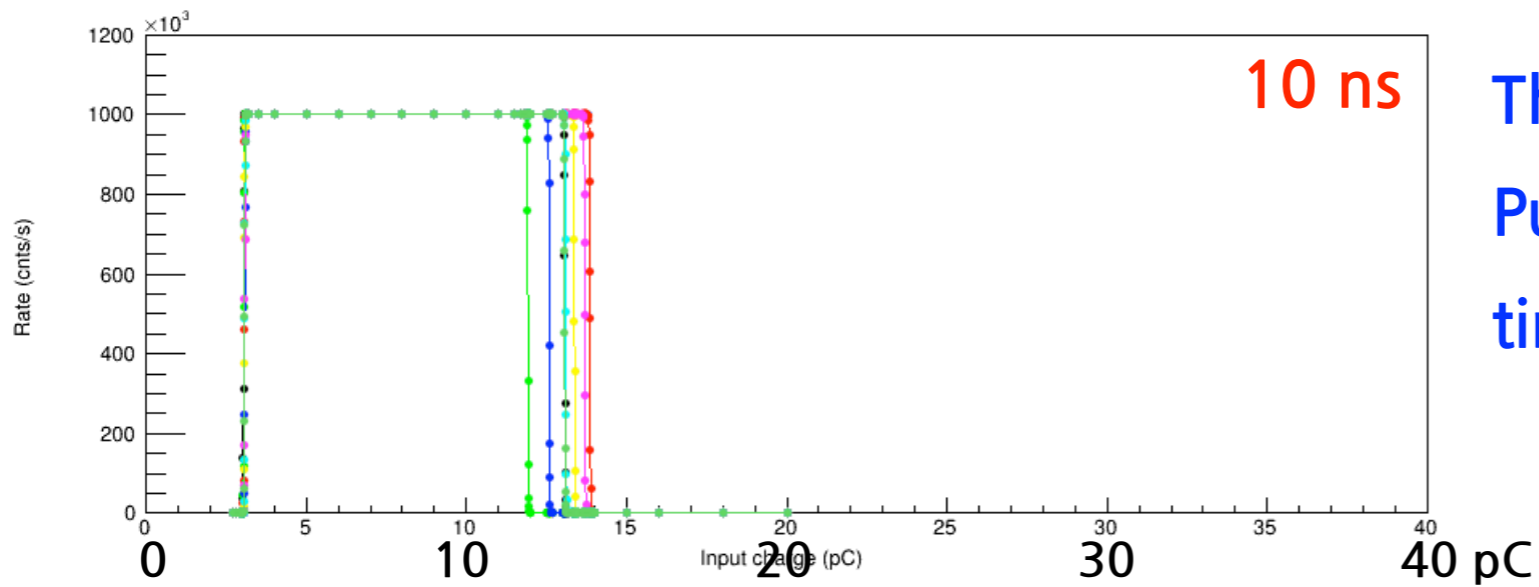
Lower threshold dispersion: $\pm 20\% \Rightarrow \pm 0.6\%$



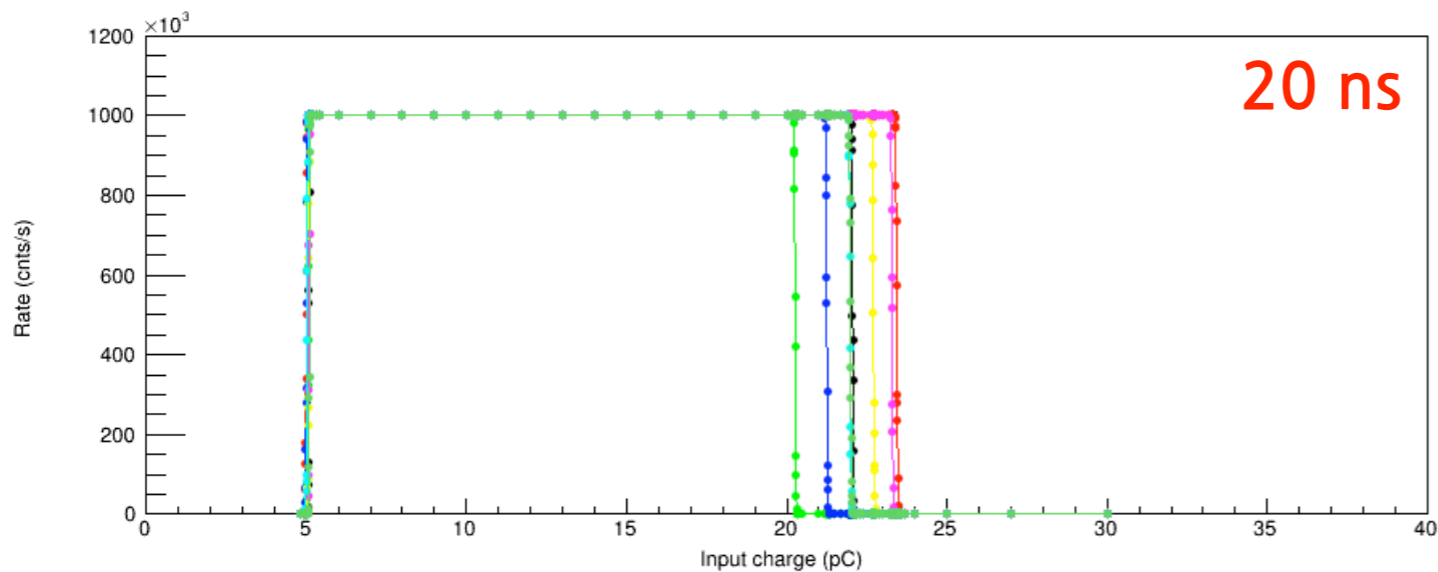
VTH0: -100 mV

VTH1: -300 mV

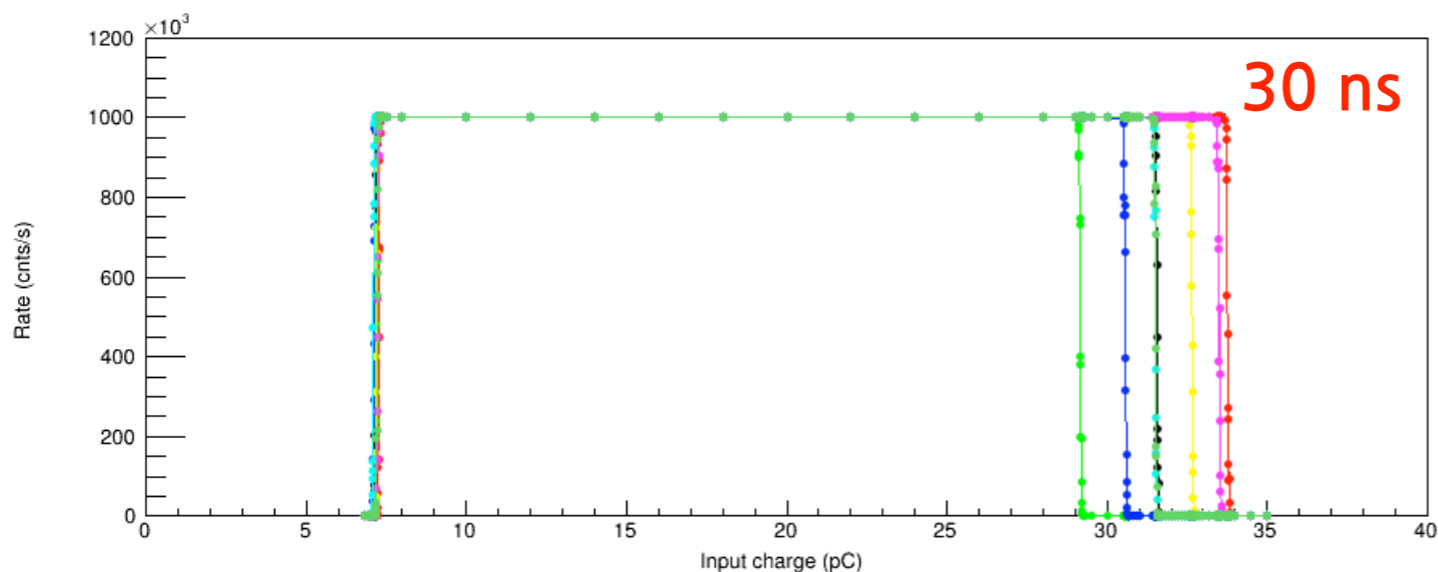
Response to different rise time



The circuit is current sensitive
Pulse height depends on the rise
time of the input signals

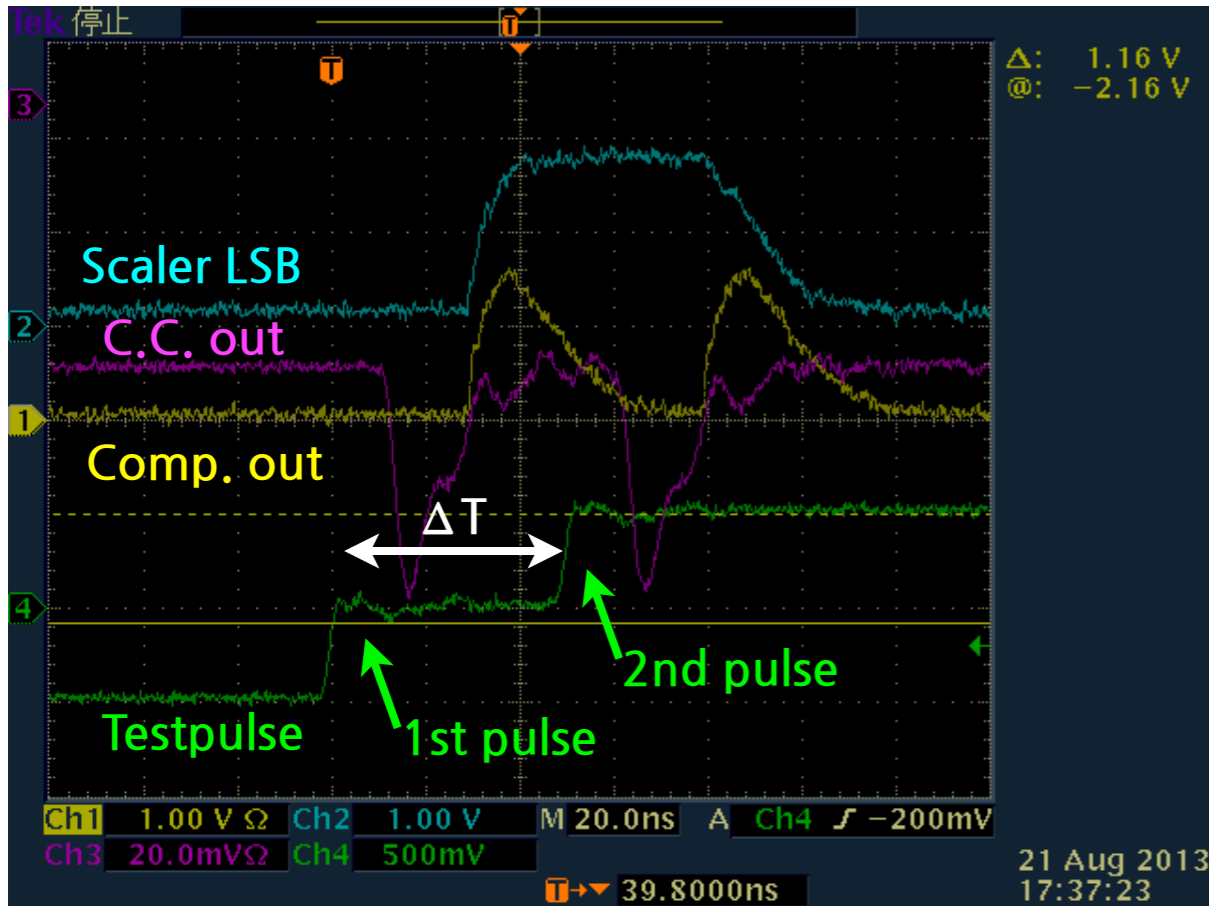


Expectation:
10-30 ns for Silicon strip detectors



Works just as expected
No problem found in this range

Double pulse experiment



Investigate how close pulses are distinguished

ΔT is changed

Fixed pulse height ~ 230 mV

Fixed V_{TH0} -200 mV

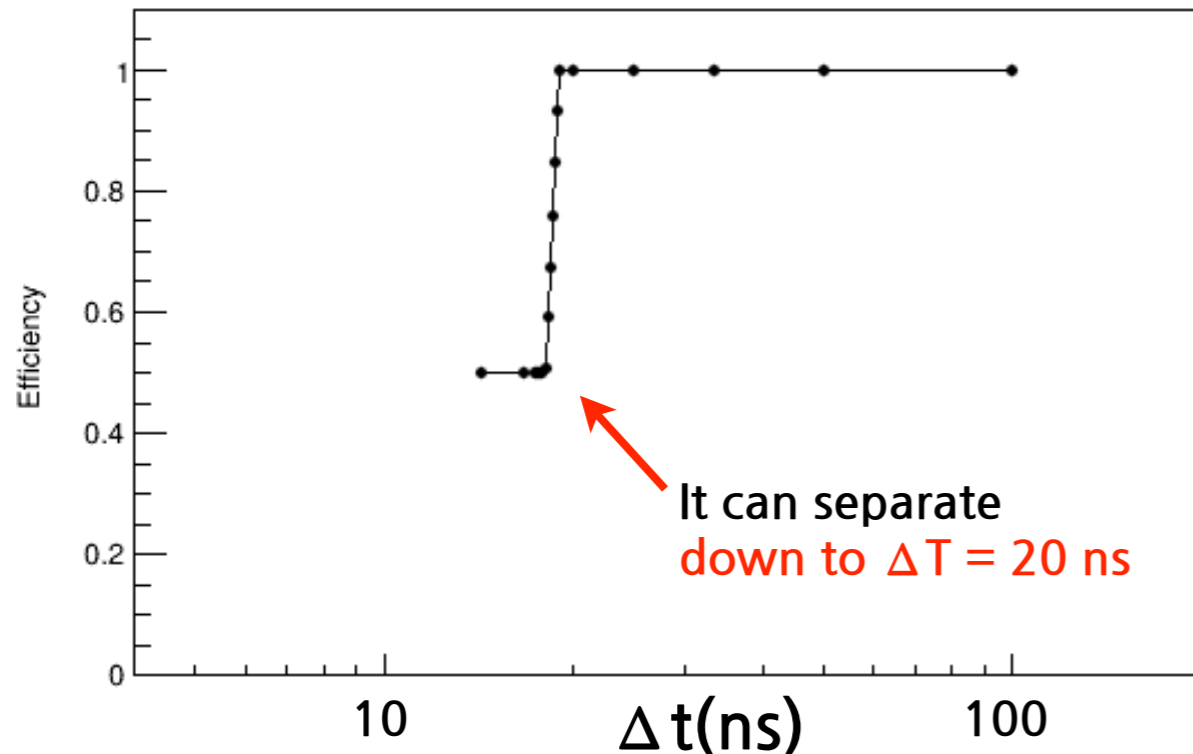
Counting efficiency is measured

Eff. = 1 : 0% loss

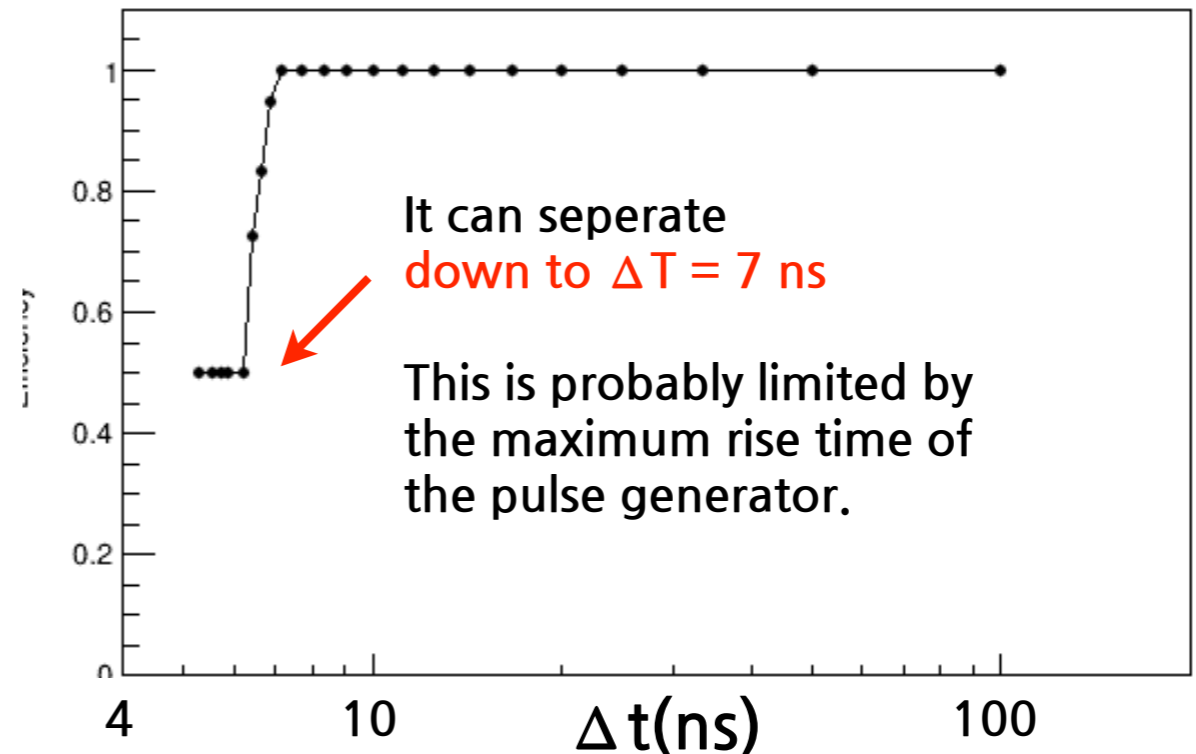
Eff. = 0.5 : Get 1st pulse, miss 2nd pulse

※ Pulse generator maximum rise time: 5 ns

Window comparator operation



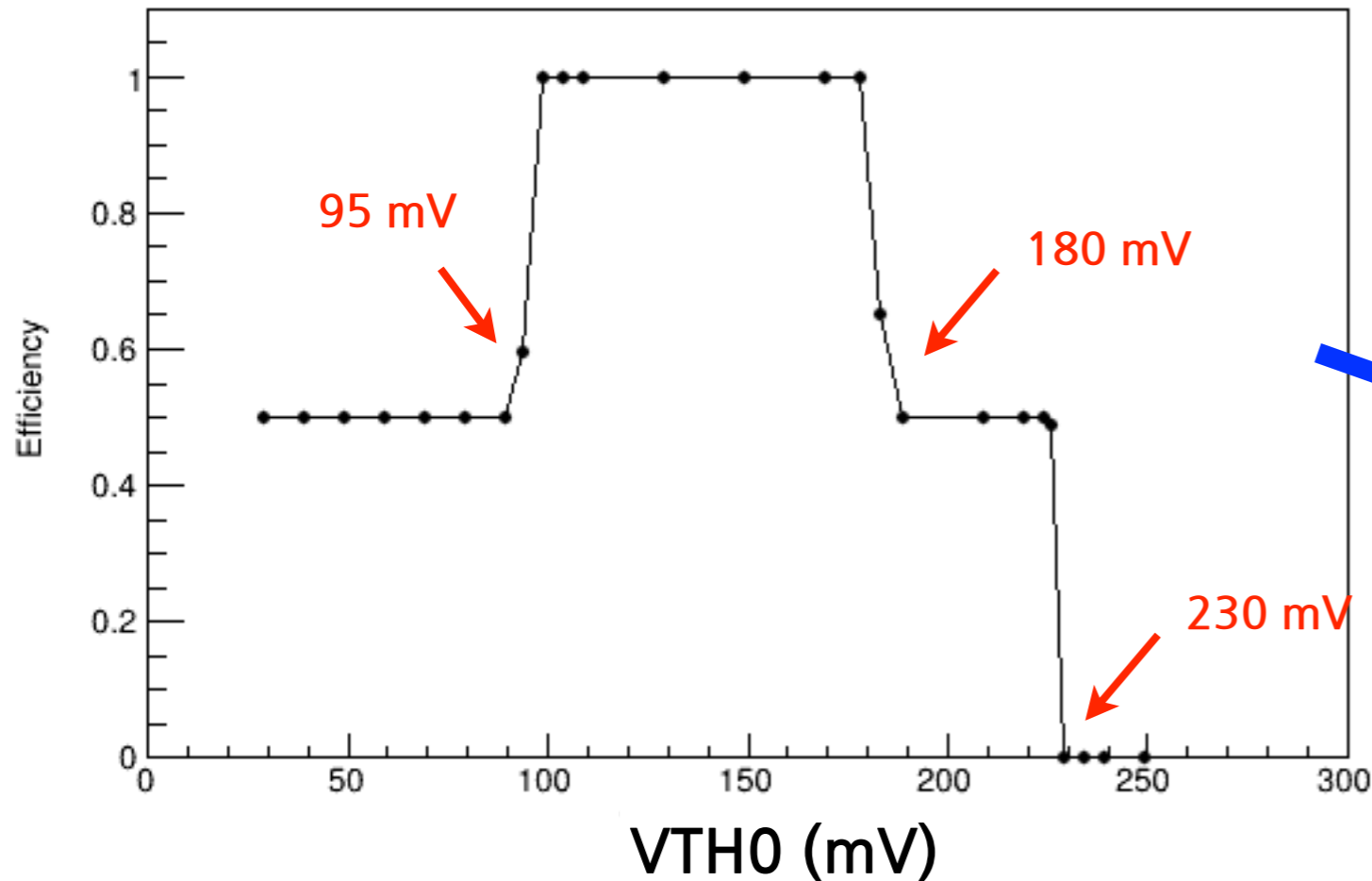
Faster response is achieved with the single comparator operation



Double pulse experiment

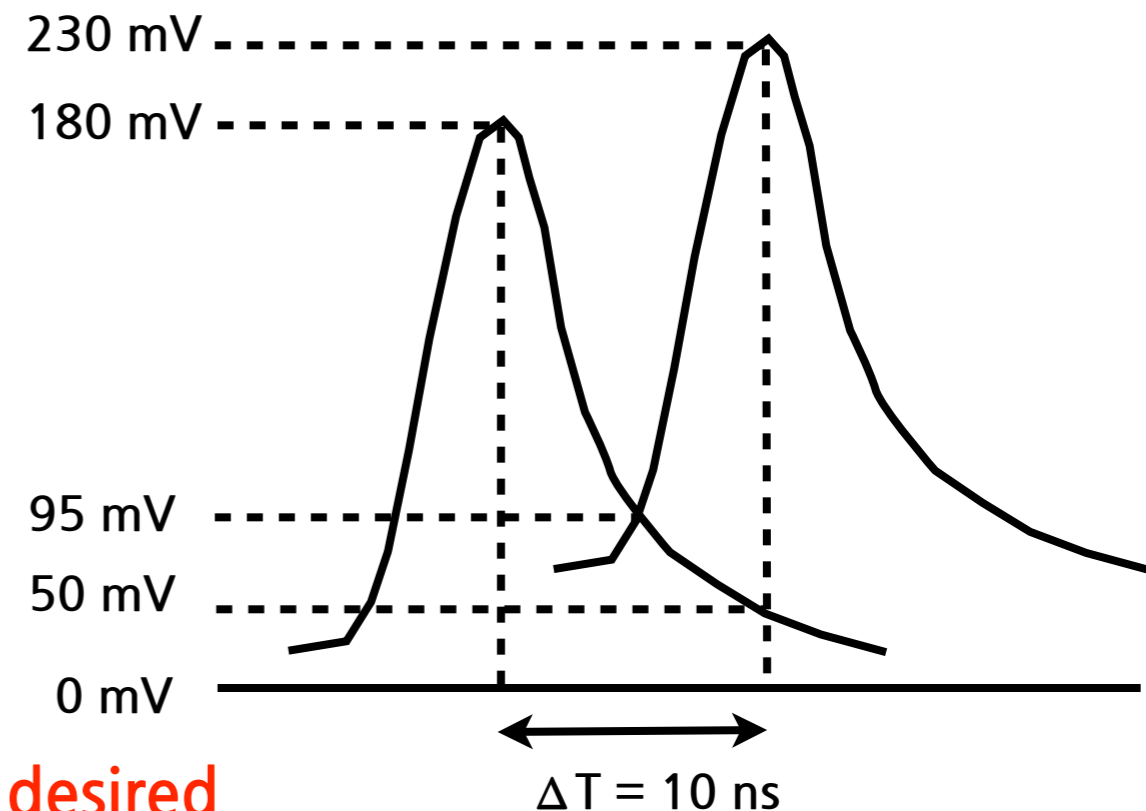
Fixed ΔT to 10 ns

Investigated dependence on V_{TH0}



※ Because of stray capacitance and probe capacitance, it is hard to observe actual pulse shape inside the ASIC.

Deduced pulse shape



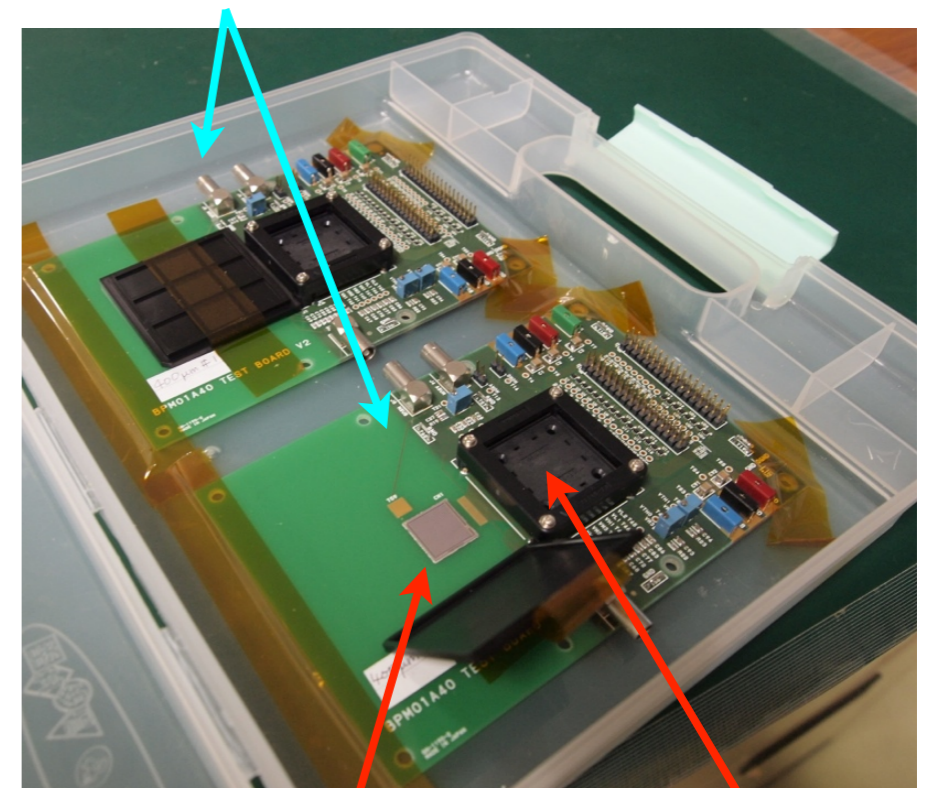
Confirmed that the signal tail is quite small as desired

Summary

- We developed high rate counting ASIC for heavy ion beam monitoring
- Circuit properties agree well between SPICE simulation and measurements
- Confirmed no loss up to 50 MHz (periodic)
- Pulse can be distinguished down to
 - 20 ns with window comp.
 - 7 ns with single comp. (maybe better)
- Future plan
 - Connect the ASICs to Si single side strip detectors
 - Place two sets of detectors in orthogonal configuration
 - Beam experiment at Gunma medical center

| | |
|--------------------|------------------------------|
| Process | XFAB 0.35 μm CMOS |
| Chip size | 8 mm x 3 mm |
| Pad pitch | 150 μm |
| Number of channels | 40 ch |
| Counter bits | 21 bits |
| Power supply | ± 1.65 V |
| Power consumption | 230 mW/chip |

Two sets of detectors will be located orthogonally



Si single side strip detector
300/400 μm pitch

ASIC